

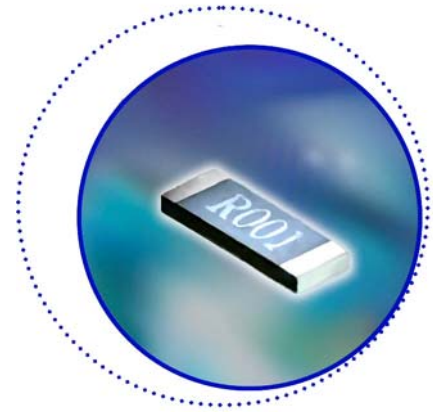
## 8W CURRENT DETECT CHIP RESISTORS

### Features

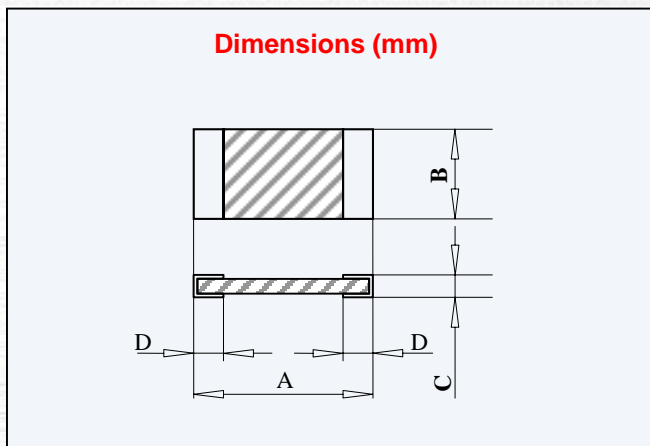
- Non inductive design.
- Low TCR, typically less than 30ppm/°C.
- Low profile surface mount package.
- Excellent pulse/surge performance.
- 8W power rating.

### Applications

- Current sense applications
- Over current protection in Battery chargers.
- Servo motor control circuits.
- DC-DC, DC-AC and intelligent power modules.
- Industrial PC modules (IPM) and precision measurement systems.
- Current detection circuits in high-speed CPU peripherals.



### Specification



Type	BCS8 (mm)
A	12.8+/-0.5
B	6.4max
C	2.5max
D	1.3

### Marking

Marking is done by 3 digits resistance value notation and tolerance code F (1%).

R001F

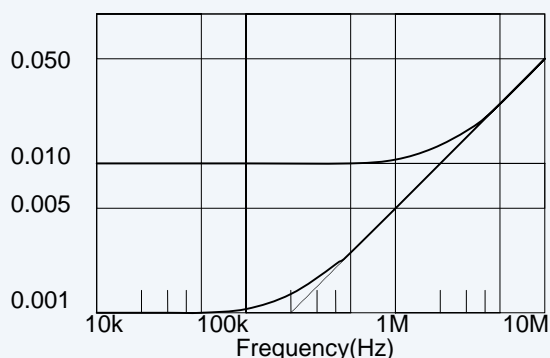
### Specification

	BCS8	Remarks
Resistance values	0.5m, 1m, 2m, 3m, 4m, 5m , 10mΩ	
TCR	+/-50ppm/°C	Measured +/- 30ppm/ °C
Tolerance	+/-1.0% (F), +/-5.0% (J)	
Power Rating	8W	Attached to70 micron PCB
Current Rating	90A	At 1m Ω
Maximum Current	126A	2.5 seconds one time
Series Inductance	5nH	
Operating Temp.	-55 C to 175 °C	
Storage Temp.	-55 C to 175 ° C	

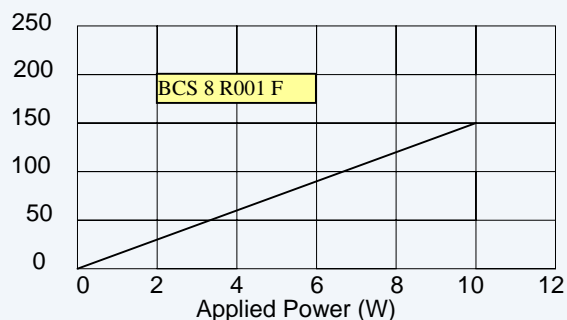
	Specifications	Conditions
Short Time Overload	$\Delta R \pm (0.5\% + 0.5m\Omega)$	maximum current, 2.5seconds.
Low Temperature Storage	$\Delta R \pm (0.5\% + 0.5m\Omega)$	-55C, 24hours
High Temperature Storage	$\Delta R \pm (1.0\% + 0.5m\Omega)$	+175C, 1000hours
Heat Shock	$\Delta R \pm (0.5\% + 0.5m\Omega)$	-55C to +125C, 20min. interval, 5min. 5cycles
Vibration	$\Delta R \pm (0.5\% + 0.5m\Omega)$	10-2000Hz, 1.5mm/20gr, 2hours
Soldering Heat	$\Delta R \pm (0.25\% + 0.5m\Omega)$	260°C+/-5°C, 10+/-1 seconds.
Solderability	90%/terminal surface	
Humidity	$\Delta R \pm (0.5\% + 0.1m\Omega)$	85°C, 85% RH, dc0.1W, 1000 hours
Load Life	$\Delta R \pm (0.5\% + 0.1m\Omega)$	25°C, dc rated power, 90min ON, 30min OFF, 1000hours

Specifications subject to change without notice.

### Frequency Characteristics

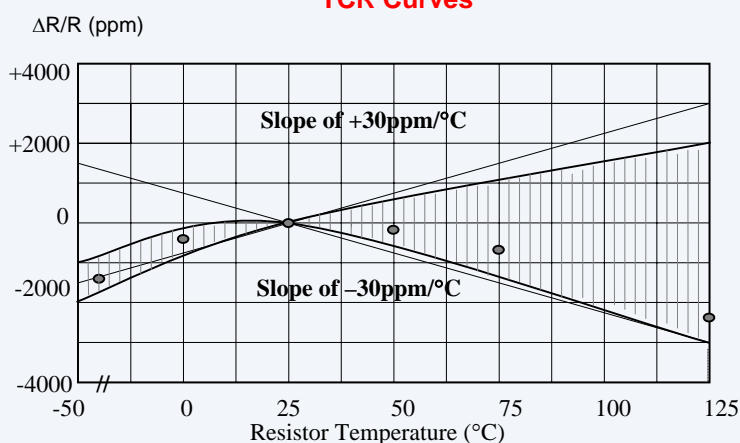
Impedance( $\Omega$ )

### Temperature Rise

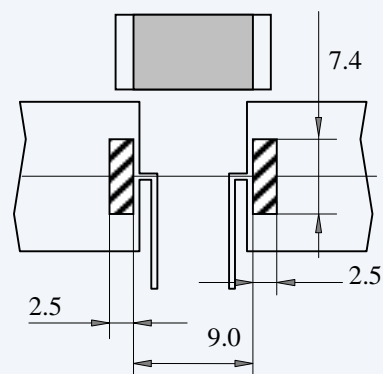
Temperature ( $^{\circ}\text{C}$ ) at hot spot.

### TCR Curves

Dotted line: typical measurement



### Recommended Foot Print (mm)



### Soldering Recommendation

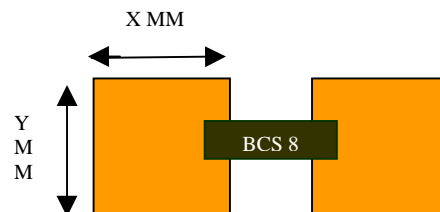
Due to the enhanced heat dissipation properties of the BCS8, the temperature profile during reflow soldering will need to be increased by: 10 to 20 $^{\circ}\text{C}$ .

### Custom designs

Alternative widths and lengths are available, please contact factory for details.

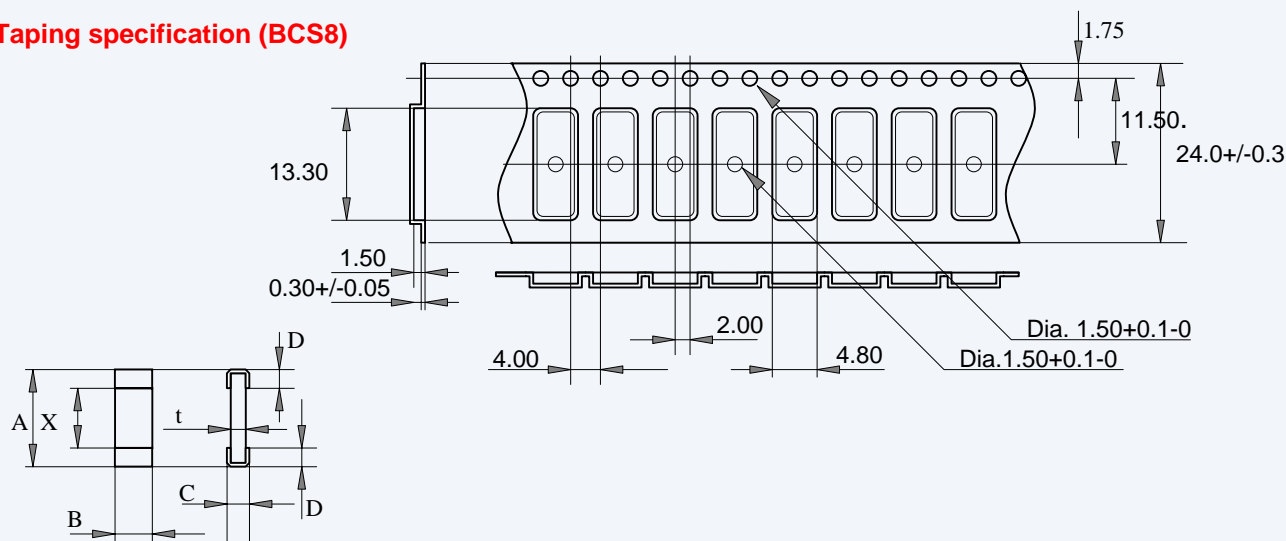
### FR4 Thermal PCB Characterisation

Pad Dimensions (x,y mm)	$P_{90^{\circ}\text{C}, 70\mu\text{m}}$ (W)	$P_{90^{\circ}\text{C}, 35\mu\text{m}}$ (W)
60, 45	5.8	4.6
50, 45	5.4	4.3
40, 40	4.2	4.1
30, 30	3.5	2.8
20, 20	2.9	2.7
10, 10	2.4	2.5



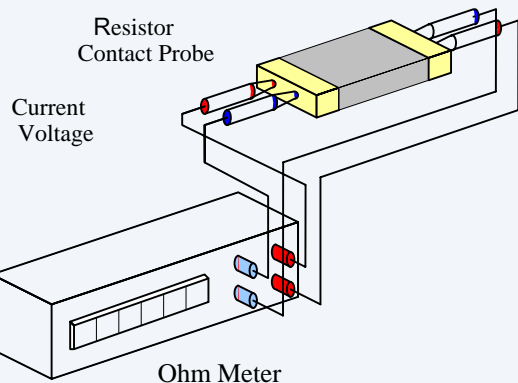
Notes: Characterisation carried out using 70 $\mu\text{m}$  and 35 $\mu\text{m}$  PCB copper pad weights, with the temperature of 90 $^{\circ}\text{C}$  used as a maximum reference on the PCB.

## Taping specification (BCS8)



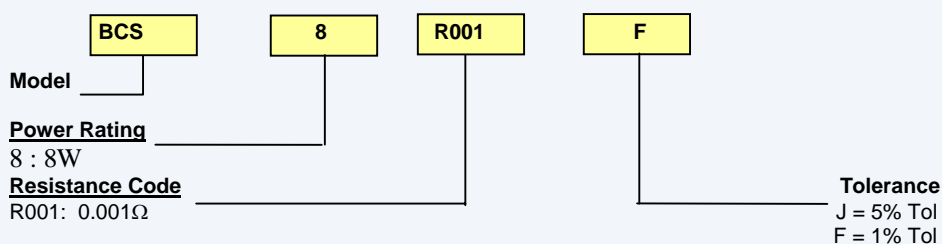
P/N	A/NA	A	B	C	D	X	t
BCS8 R001F	A	12.8	4.0	1.14	1.4	10.0	1.0
BCS8 R002F	A	12.8	4.0	0.64	1.4	10.0	0.5
BCS8 R003F	A	12.8	2.7	0.64	1.4	10.0	0.5
BCS8 R003F	A	12.8	4.5	0.44	1.4	10.0	0.3
BCS8 R004F	NA	12.8	5.3	0.34	1.4	10.0	0.2
BCS8 R005F	A	12.8	4.4	0.34	1.4	10.0	0.2

Note : Above dimensions are approximate.



Resistance testing the BCS resistors is done at the side positions of resistor terminals (see figure) using a 4 - port measuring system. For a stated resistance tolerance of  $\pm 1.0\%$ , the measured values should be within the  $\pm 0.8\%$  factory tested values. When surface mount resistor is attached on circuit board, small resistance changes will occur, Custom designs are available, please call the factory.

## Ordering Information



BCS 8